

JP 11-017074

AN 1999:56919 CAPLUS
 DN 130:183514
 TI Oxetane-containing potting compositions and semiconductor devices
 IN Chiba, Hideki; Ito, Tomokazu; Shiota, Atsushi; Sato, Hozumi
 PA JSR Co., Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 9 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC ICM H01L023-29
 ICS H01L023-31; C08L071-02
 CC 38-3 (Plastics Fabrication and Uses)
 Section cross-reference(s): 76

409
withdrawn

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
✓ PI	JP 11017074	A2	19990122	JP 1997-185822	19970626
AB	The compns. contain oxetane compds. Thus, a compn. contg. 99 parts XDO [1,4-bis[(3-ethyl-3-oxetanylmethoxy)methyl]benzene] and 1 part San-Aid SI 100 (sulfonium salt curing catalyst) showed gelation time 4.3, 0.5, and 0.1 min at 75, 100, and 125.degree., resp., high fluidity, and low viscosity at 75.degree. and gave cured products after heating at 125.degree. for 35 min with low linear expansion coeff.				
ST	thermosetting oxetane polymer semiconductor device potting				
IT	Electronic packaging materials Potting compositions Semiconductor devices (oxetane-contg. potting compns. and semiconductor devices)				
IT	Polyoxyalkylenes, uses RL: DEV (Device component use); IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (oxetane-contg. potting compns. and semiconductor devices)				
IT	Novolaks RL: DEV (Device component use); IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (polymers with oxetane derivs.; oxetane-contg. potting compns. and semiconductor devices)				
IT	142627-97-2DP, polymers with phenolic novolak resin 142675-47-6P 167488-42-8P 210093-34-8P 220527-99-1P RL: DEV (Device component use); IMF (Industrial manufacture); PRP (Properties); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses) (oxetane-contg. potting compns. and semiconductor devices)				

WEST**End of Result Set**

Generate Collection

L1: Entry 1 of 1

File: DWPI

Jan 22, 1999

DERWENT-ACC-NO: 1999-159589
DERWENT-WEEK: 199918
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TITLE: Composition for sealing semiconductor - containing oxetane compound

PATENT-ASSIGNEE:

ASSIGNEE

CODE

NIPPON GOSEI GOMU KK

JAPS

PRIORITY-DATA:

1997JP-0185822

June 26, 1997

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<u>JP 11017074 A</u>	January 22, 1999	N/A	009	H01L023/29

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-NO
JP11017074A	June 26, 1997	1997JP-0185822	N/A

INT-CL (IPC): C08L 71/02; H01L 23/29; H01L 23/31

ABSTRACTED-PUB-NO: JP11017074A

BASIC-ABSTRACT:

A composition contains an oxetane compound. Also claimed is a semiconductor is sealed by the hardened material of the composition.

USE - The compsn. is partic. used in the semiconductor device having a semiconductor integrated circuit-formed chip, a chip-mounted element substrate, an electrical connection portion formed between the substrate and an electrode terminal facing the chip, and a resin layer formed by filling voids around the electrical connection portion.

ADVANTAGE - The use of the oxetane cpd. provides the compsn. with high fluidity and quick hardening. The resulting compsn. is filled in fine voids. The use of the compsn. yields the semiconductor device suitable for high-density mounting.

CHOSEN-DRAWING: Dwg.0/2

TITLE-TERMS: COMPOSITION SEAL SEMICONDUCTOR CONTAIN OXETANE COMPOUND

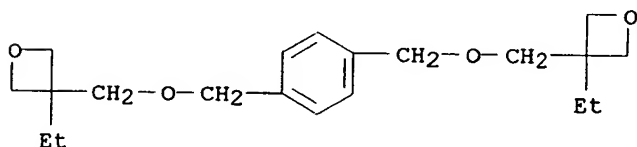
DERWENT-CLASS: A85 E13 L03 U11

CPI-CODES: A11-B05; A12-E04; A12-E07C; E07-A03C; L04-C20A;

EPI-CODES: U11-E02A2;

CHEMICAL-CODES:

RN 142627-97-2 REGISTRY
 CN Oxetane, 3,3'-[1,4-phenylenebis(methyleneoxymethylene)]bis[3-ethyl- (9CI)
 (CA INDEX NAME)
 OTHER NAMES:
 CN 1,4-Bis[(3-ethyl-3-oxetanylmethoxy)methyl]benzene
 CN 3,3'-(1,4-Xylenediylbis(oxymethylene))bis(3-ethyloxetane)
 CN 3,3'-(p-Xylylene-dioxymethyl)bis(3-ethyloxetane)
 FS 3D CONCORD
 MF C20 H30 O4
 CI COM
 SR CA
 LC STN Files: CA, CAPLUS, TOXLIT, USPATFULL



19 REFERENCES IN FILE CA (1967 TO DATE)
 2 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
 20 REFERENCES IN FILE CAPLUS (1967 TO DATE)